



N-Channel Enhancement Mode Field Effect Transistor

● **Features**

$V_{DS} (V) = 40V$

$I_D = 15A (V_{GS} = 10V)$

$R_{DS(ON)} < 9.5m\Omega (V_{GS} = 10V)$

$R_{DS(ON)} < 15.5m\Omega (V_{GS} = 4.5V)$

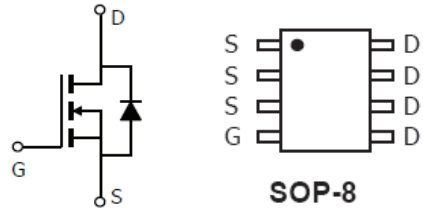
● **General Description**

The HX4480SQ uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

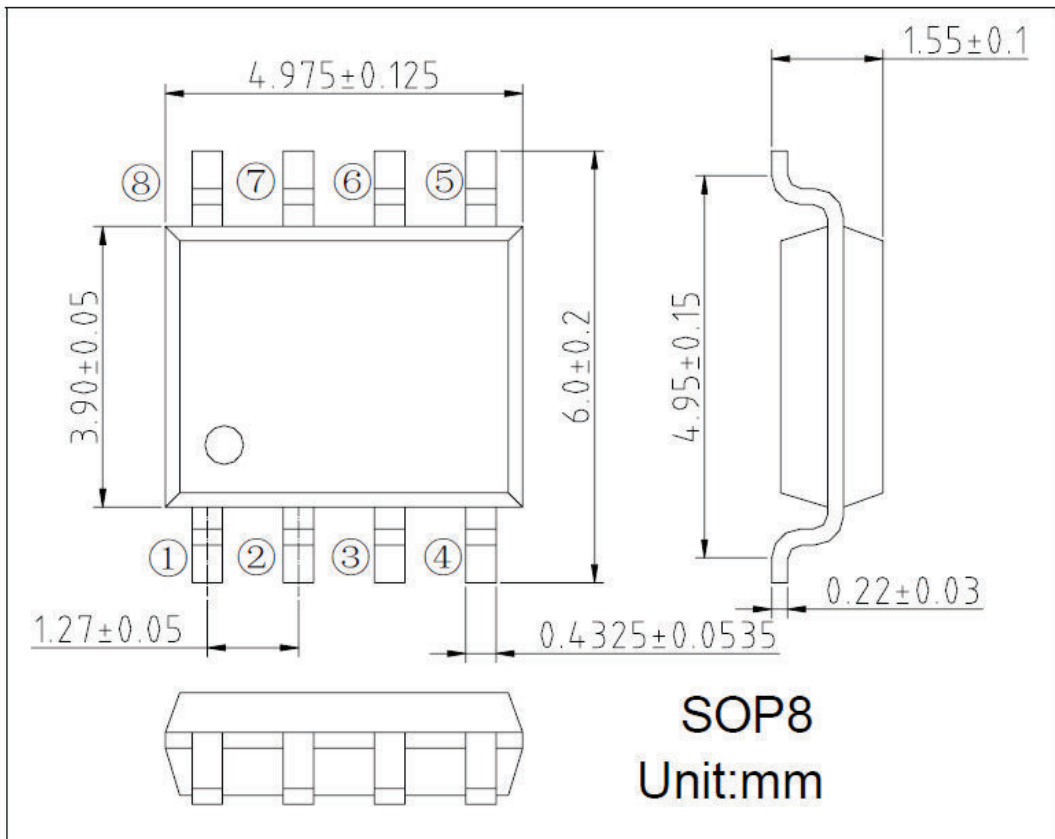
-RoHS Compliant

-Halogen Free

● **Pin Configurations**



● **Package Information**





● **Absolute Maximum Ratings @ $T_A=25^{\circ}\text{C}$ unless otherwise noted**

Parameter	Symbol	Ratings	Unit
Drain-Source Voltage	V_{DSS}	40	V
Gate-Source Voltage	V_{GSS}	± 20	V
Drain Current (Continuous) *AC	I_D	$T_A=25^{\circ}\text{C}$	15
		$T_A=70^{\circ}\text{C}$	12
Drain Current (Pulse) *B	I_{DM}	40	A
Power Dissipation	P_D	$T_A=25^{\circ}\text{C}$	3
		$T_A=70^{\circ}\text{C}$	2.1
Operating Temperature/ Storage Temperature	T_J/T_{STG}	-55~150	$^{\circ}\text{C}$

● **Electrical Characteristics @ $T_A=25^{\circ}\text{C}$ unless otherwise noted**

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Static						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D=250 \mu A$	40	--	--	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 40V, V_{GS} = 0V$	--	--	1	μA
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_{DS}=250 \mu A$	1	1.8	3	V
Gate Leakage Current	I_{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V$	--	--	100	nA
Drain-Source On-state Resistance	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 15A$	--	7.3	9.5	$m\Omega$
		$V_{GS} = 4.5V, I_D = 11A$	--	11	15.5	$m\Omega$
Forward Transconductance	g_{FS}	$V_{DS}=5V, I_D=15A$	--	45	--	S
Diode Forward Voltage	V_{SD}	$I_{SD}=1A, V_{GS}=0V$	--	0.71	1.0	V
Maximum Body-Diode Continuous Current	I_S		--	--	5	A
Switching						
Total Gate Charge	Q_g	$V_{GS}=5V, V_{DS}=15V, I_D=14A$	--	16	20.8	nC
Gate-Source Charge	Q_{gs}		--	5	6.5	nC
Gate-Drain Charge	Q_{gd}		--	3	3.9	nC
Turn-on Delay Time	$t_{d(on)}$	$V_{GS}=10V, V_{DS}=15V, R_L=15\Omega, R_{GEN}=6\Omega$	--	17	34	ns
Turn-on Rise Time	t_r		--	5	10	ns
Turn-off Delay Time	$t_{d(off)}$		--	50	100	ns
Turn-off Fall Time	t_f		--	10	20	ns
Dynamic						
Input Capacitance	C_{iss}	$V_{GS}=0V, V_{DS}=15V, f=1MHz$	--	2470	--	pF
Output Capacitance	C_{oss}		--	325	--	pF
Reverse Transfer Capacitance	C_{rss}		--	185	--	pF

A: The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^{\circ}\text{C}$. The value in any given application depends on the user's specific board design.

B: Repetitive rating, pulse width limited by junction temperature.

C: The current rating is based on the $t \leq 10s$ junction to ambient thermal resistance rating.



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

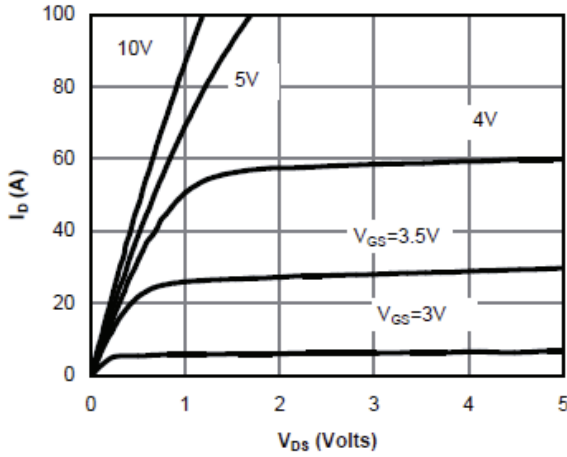


Figure 1: On-Region Characteristics

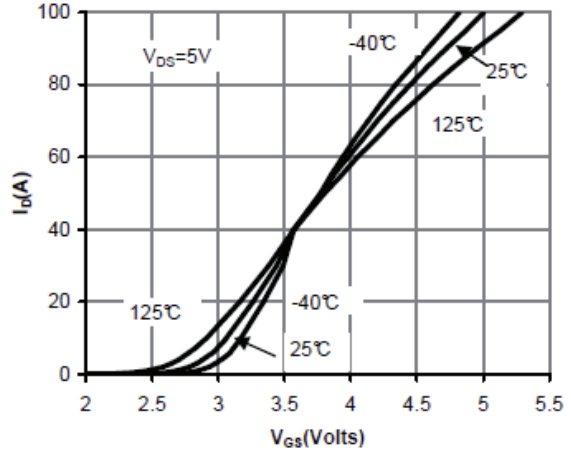


Figure 2: Transfer Characteristics

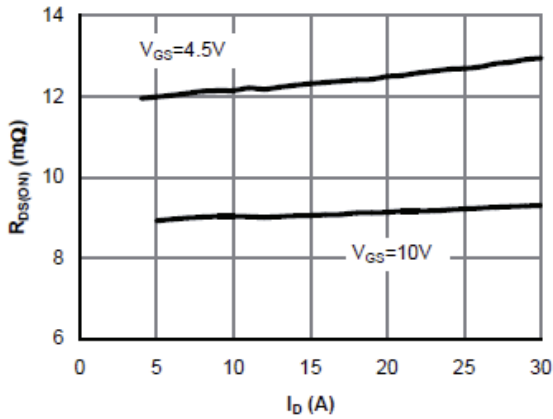


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

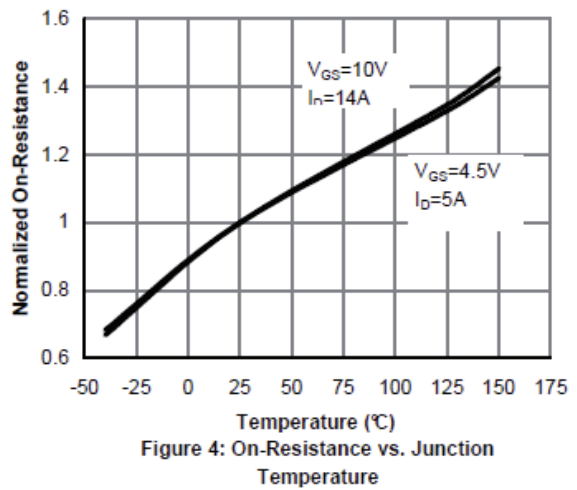


Figure 4: On-Resistance vs. Junction Temperature

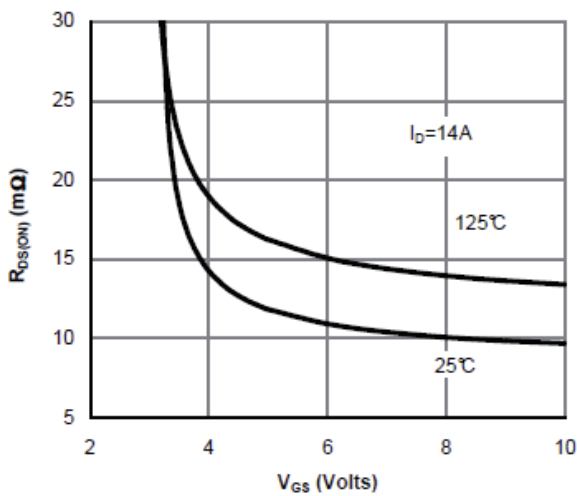


Figure 5: On-Resistance vs. Gate-Source Voltage

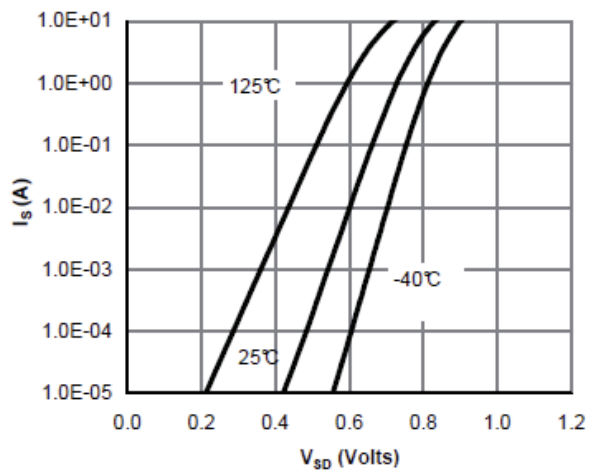


Figure 6: Body-Diode Characteristics

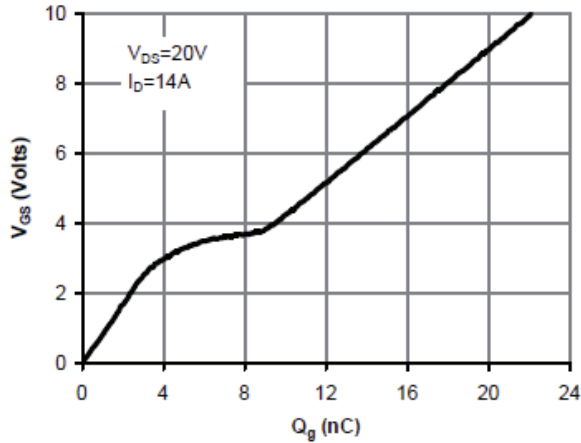


Figure 7: Gate-Charge Characteristics

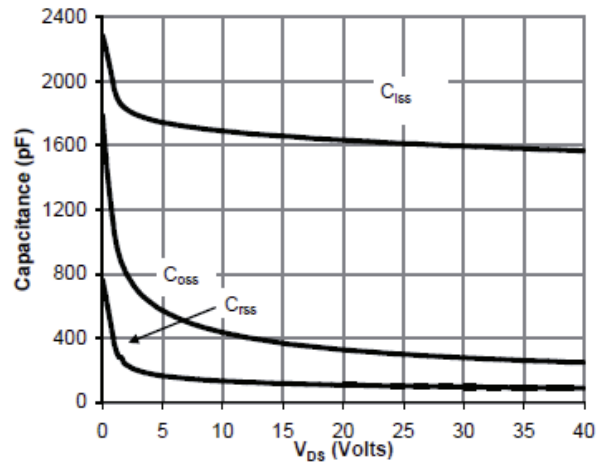


Figure 8: Capacitance Characteristics

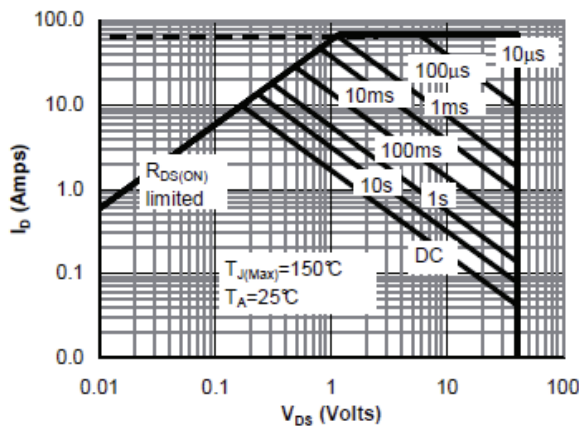


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

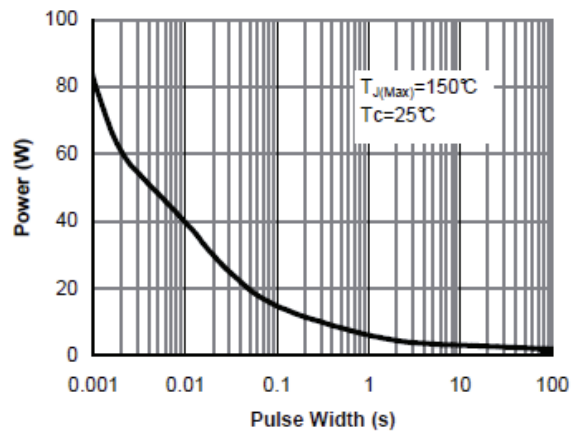


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note F)

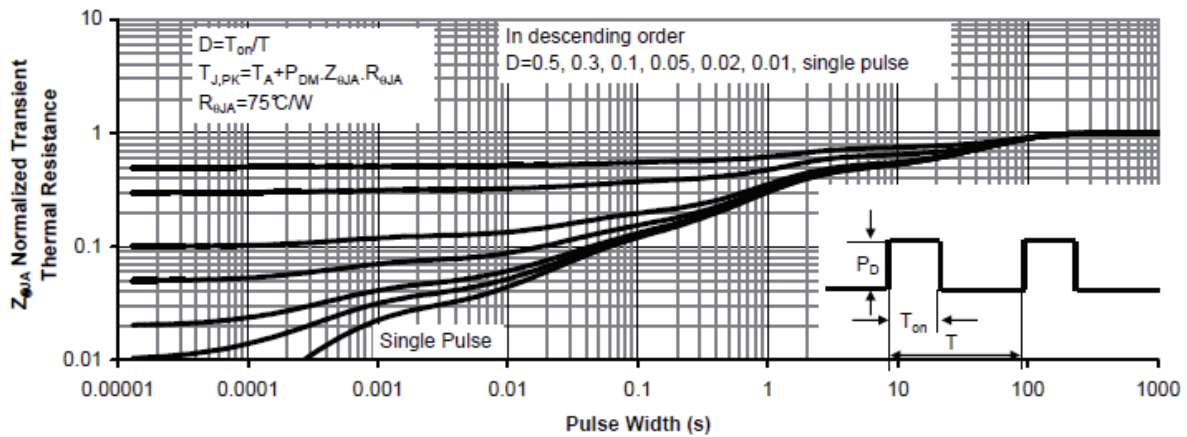


Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)